

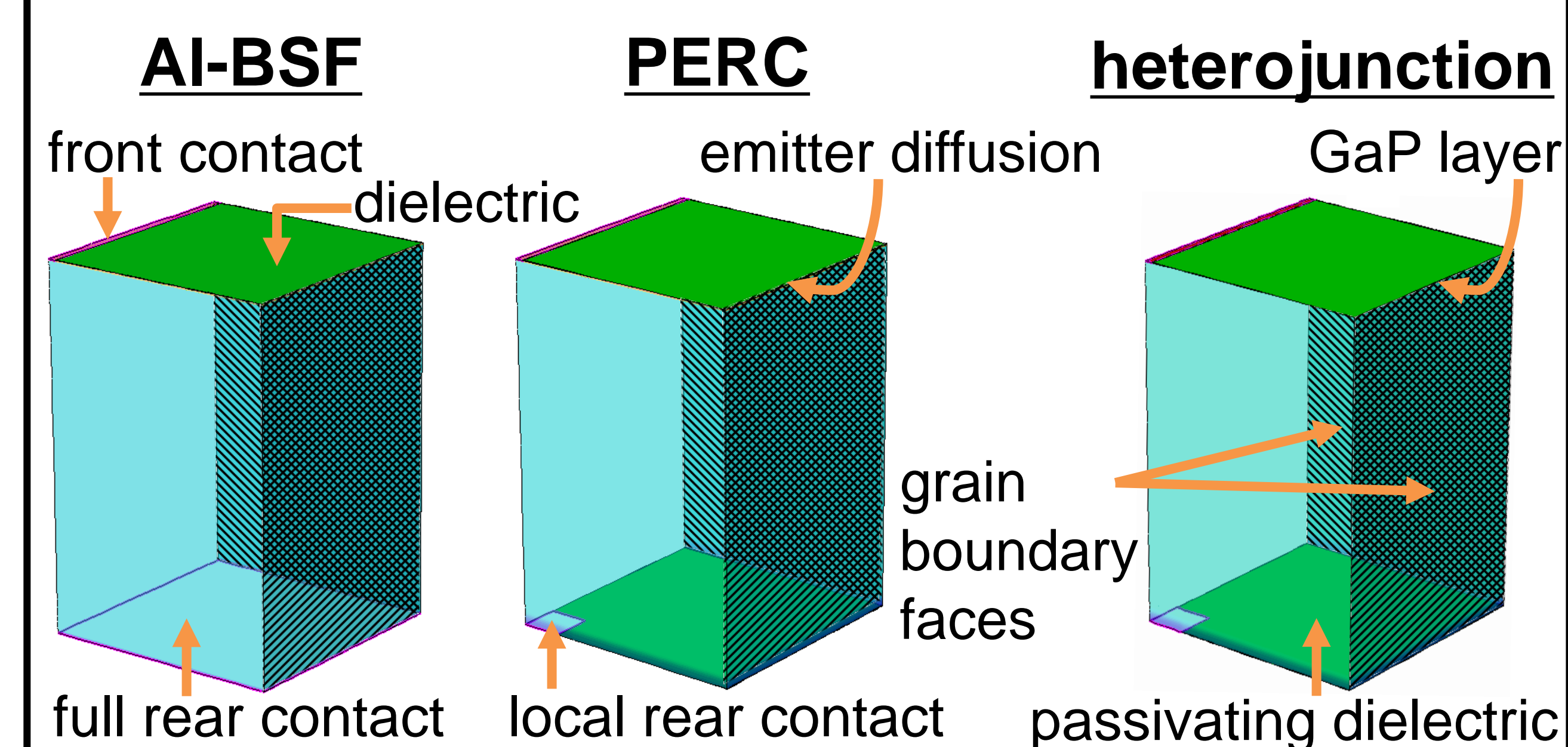
# 2-D and 3-D TCAD simulations of defect-tolerant solar cell architectures

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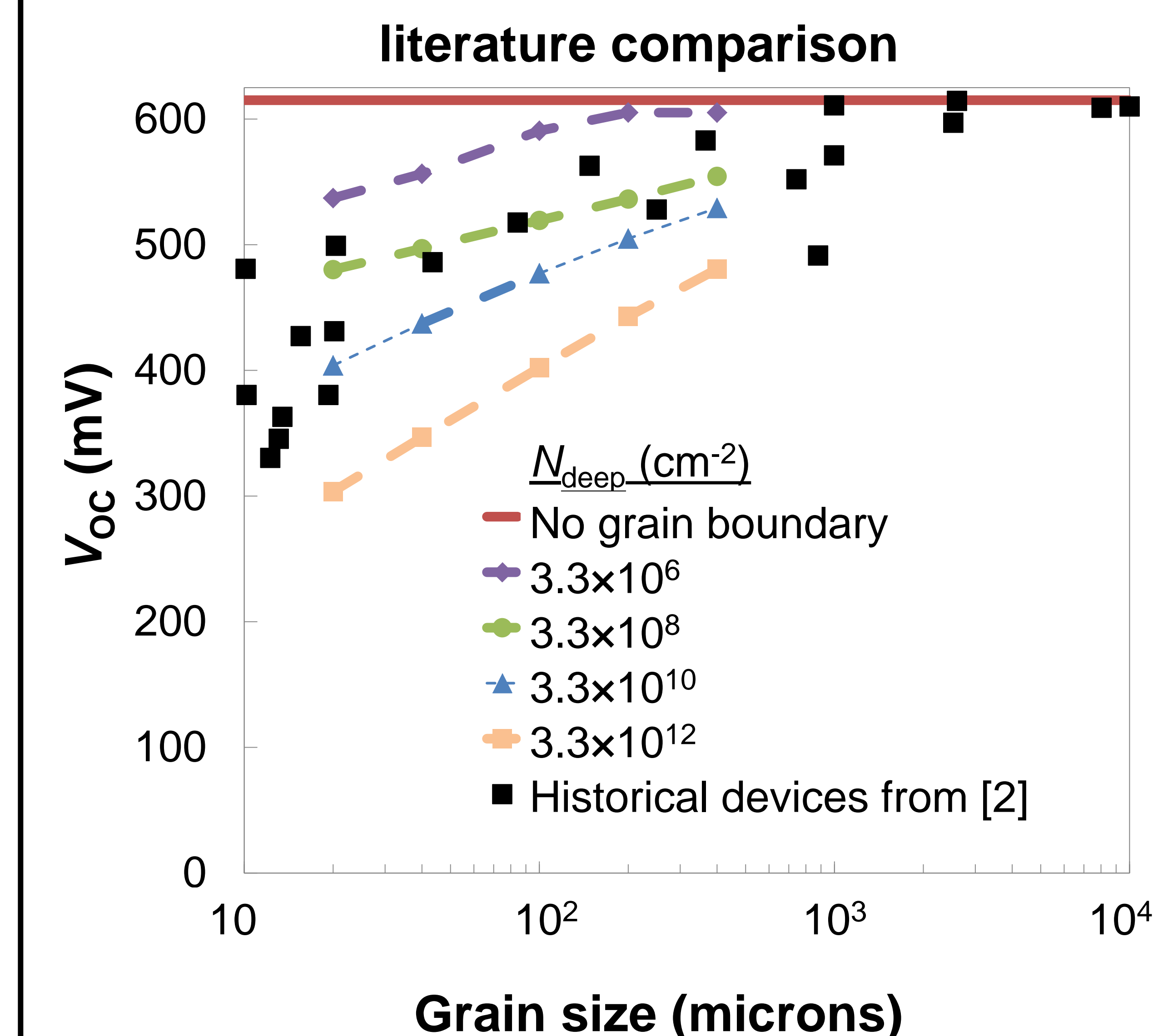
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- We use 2-D and 3-D TCAD simulations in Sentaurus Device to determine the injection-dependent device performance impacts of point defects (e.g.,  $\text{Fe}_i$ ) and extended defects (e.g., grain boundaries).
- We identify features of device design that contribute to defect tolerance.

## grain boundary model

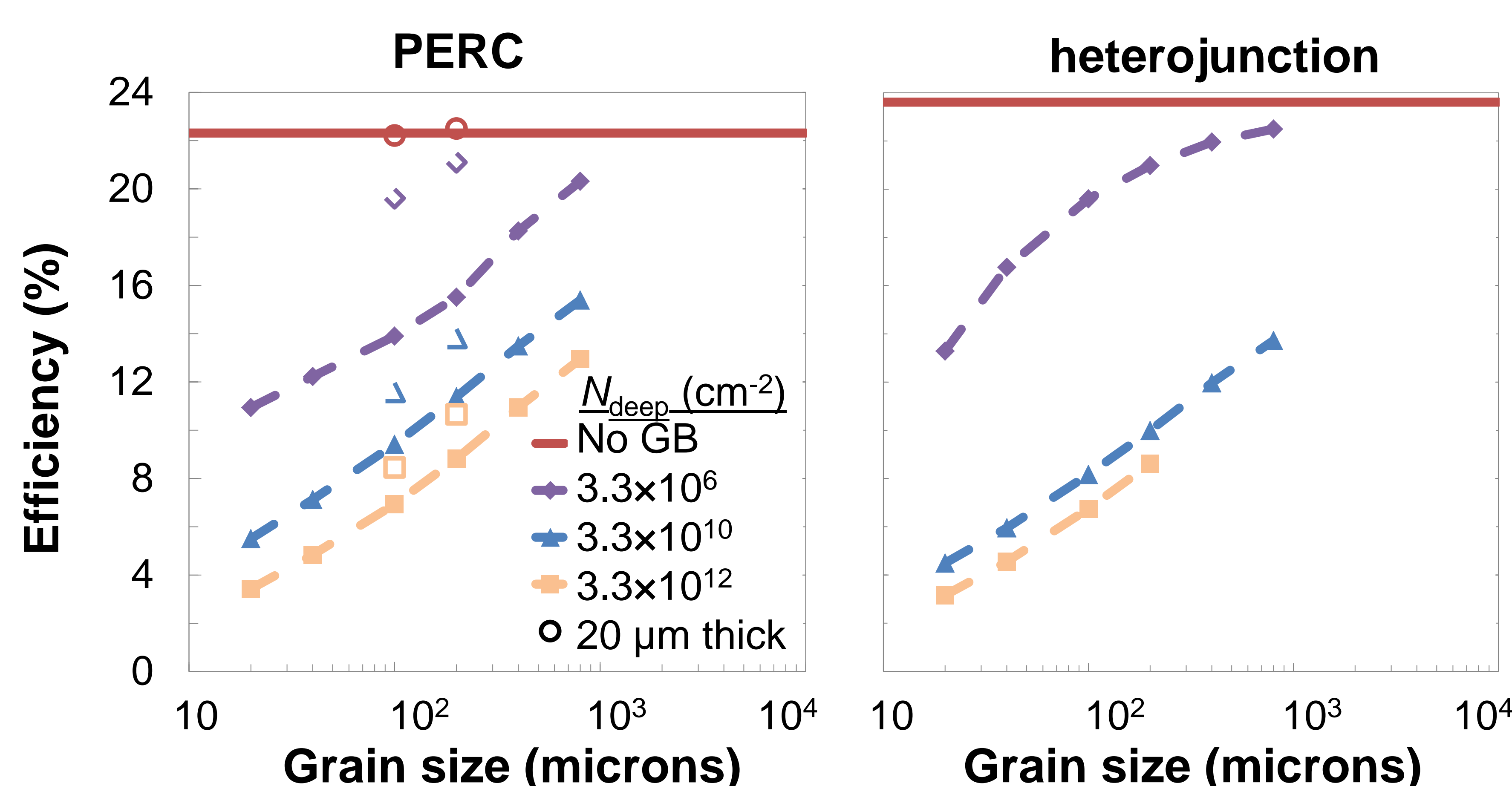


- We model grain boundaries in 3-D as mid-gap recombination centers ( $N_{\text{deep}}$ ) at an interface 2 nm from the simulated domain boundary [1].
- Modified capture cross-sections account for defect charging.

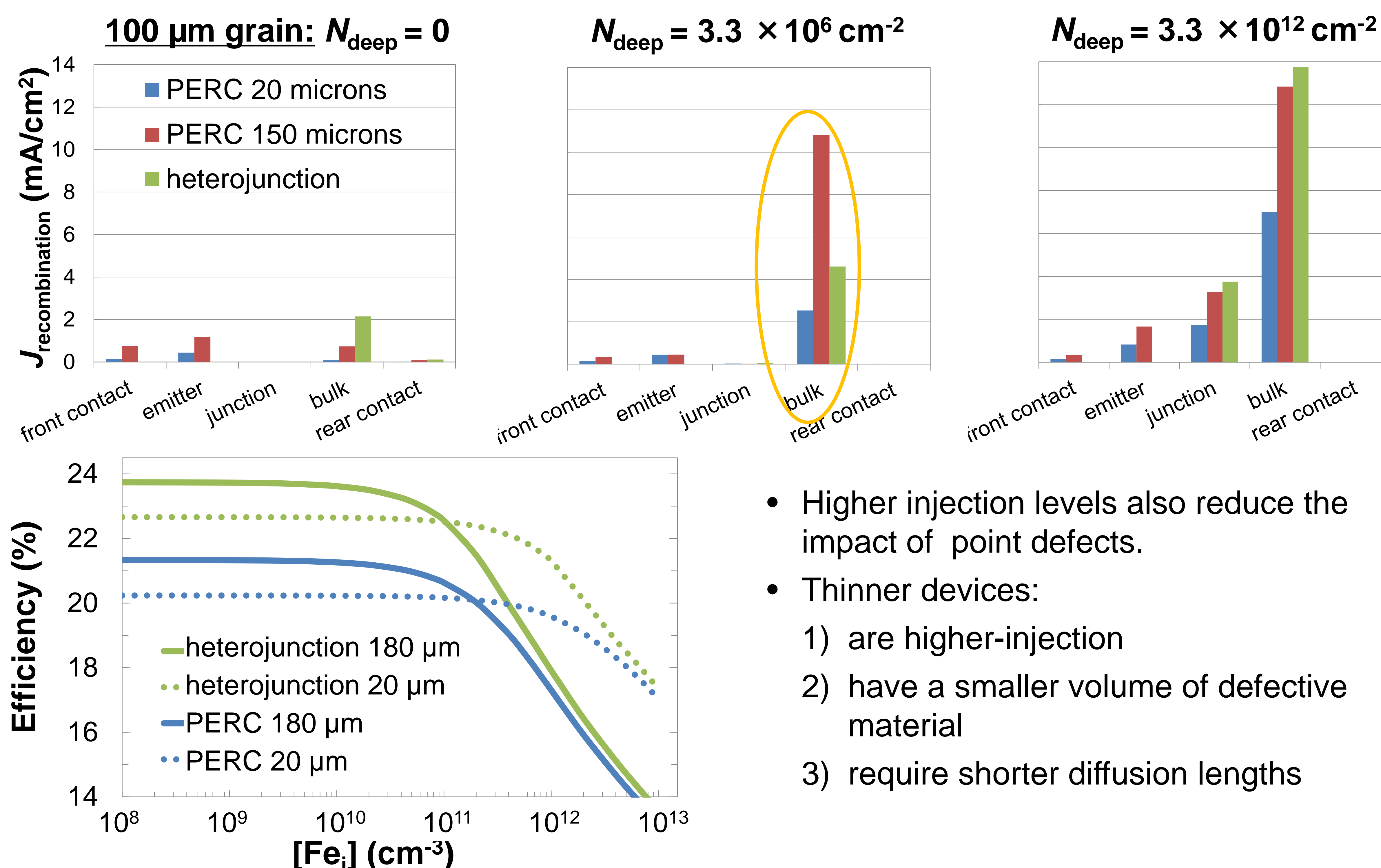


- Our simulated Al-BSF device agrees well with experimental results from literature [2].

## heterojunction vs. thick and thin PERC



- Heterojunction more tolerant to  $N_{\text{deep}}$  at grain boundary.
- 20  $\mu\text{m}$  thin PERC more defect-tolerant at all decoration concentrations.
- $\uparrow$  injection  $\rightarrow \downarrow$  charging  $\rightarrow \downarrow$  bulk recombination in heterojunction.
- 20  $\mu\text{m}$  thin PERC *not* in high injection.



- Higher injection levels also reduce the impact of point defects.
- Thinner devices:
  - are higher-injection
  - have a smaller volume of defective material
  - require shorter diffusion lengths

### References:

- [1] D. Berney Needleman, H. Wagner, P.P. Altermatt, and T. Buonassisi, *Energy Procedia* (accepted) DOI: 10.1016/j.egypro.2015.07.003.  
[2] P.P. Altermatt and G. Heiser, *J. Appl. Phys.* **91** 4271 (2002).

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